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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details

Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	-
Number of Macrocells	256
Number of Gates	-
Number of I/O	120
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	160-BQFP
Supplier Device Package	160-PQFP (28x28)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/m5-256-120-15yc-1

**Select devices have been discontinued.
See Ordering Information section for product status.**

Table 1. MACH 5 Device Features¹

Feature	M5-128/1 M5LV-128		M5-192/1		M5-256/1 M5LV-256		M5-320 M5LV-320		M5-384 M5LV-384		M5-512 M5LV-512	
Supply Voltage (V)	5	3.3	5	5	3.3	5	3.3	5	3.3	5	3.3	
Macrocells	128	128	192	256	256	320	320	384	384	512	512	
Maximum User I/O Pins	120	120	120	160	160	192	160	160	160	256	256	
t _{PD} (ns)	5.5	5.5	5.5	5.5	5.5	6.5	6.5	6.5	6.5	6.5	6.5	
t _{SS} (ns)	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	3.0	
t _{COS} (ns)	4.5	4.5	4.5	4.5	4.5	5.0	5.0	5.0	5.0	5.0	5.0	
f _{CNT} (MHz)	182	182	182	182	182	167	167	167	167	167	167	
Typical Static Power (mA)	35	35	45	55	55	70	70	75	75	100	100	
IEEE 1149.1 Boundary Scan Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	
PCI-Compliant	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	Yes	

Note:

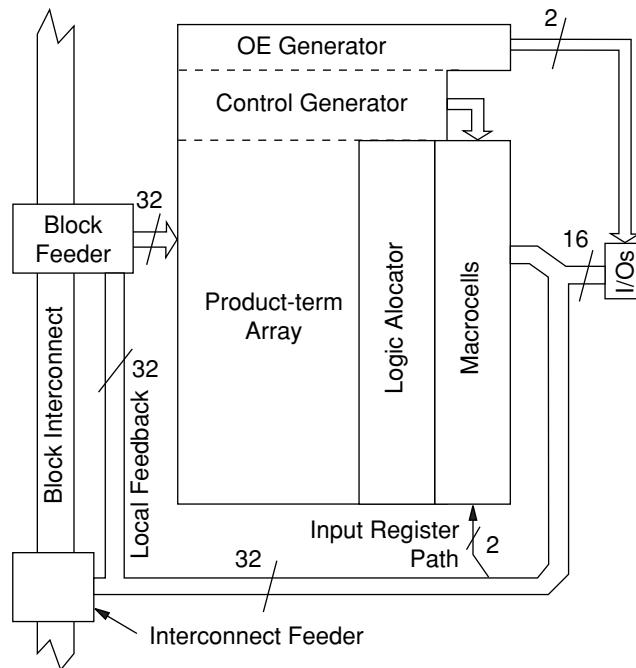
1. "M5-xxxx" is for 5-V devices. "M5LV-xxxx" is for 3.3-V devices.

GENERAL DESCRIPTION

The MACH® 5 family consists of a broad range of high-density and high-I/O Complex Programmable Logic Devices (CPLDs). The fifth-generation MACH architecture yields fast speeds at high CPLD densities, low power, and supports additional features such as in-system programmability, Boundary Scan testability, and advanced clocking options (Table 1). The MACH 5 family offers 5-V (M5-xxx) and 3.3-V (M5LV-xxx) operation.

Manufactured in state-of-the-art ISO 9000 qualified fabrication facilities on E²CMOS process technologies, MACH 5 devices are available with pin-to-pin delays as fast as 5.5 ns (Table 2). The 5.5, 6.5, 7.5, 10, and 12-ns devices are compliant with the *PCI Local Bus Specification*.

Select devices have been discontinued.
See Ordering Information section for product status.



20446G-002

Figure 2. PAL Block Structure

Product-Term Array and Logic Allocator

The product-term array uses the same sum-of-products architecture as PAL devices and consists of 32 inputs (plus their complements) and 64 product terms arranged in 16 **clusters**. A cluster is a sum-of-products function with either 3 or 4 product terms.

Logic allocators assign the clusters to macrocells. Each macrocell can accept up to eight clusters of three or four product terms, but a given cluster can only be steered to one macrocell (Table 4). If only three product terms in a cluster are steered, the fourth can be used as an input to an XOR gate for separate logic generation and/or polarity control.

The **wide logic allocator** is comprised of all 16 of the individual logic allocators and acts as an output switch matrix by reassigning logic to macrocells to retain pinout as designs change. The logic allocation scheme in the MACH 5 device allows for the implementation of large equations (up to 32 product terms) with only one pass through the logic array.

Table 4. Product Term Steering Options for PT Clusters and Macrocells

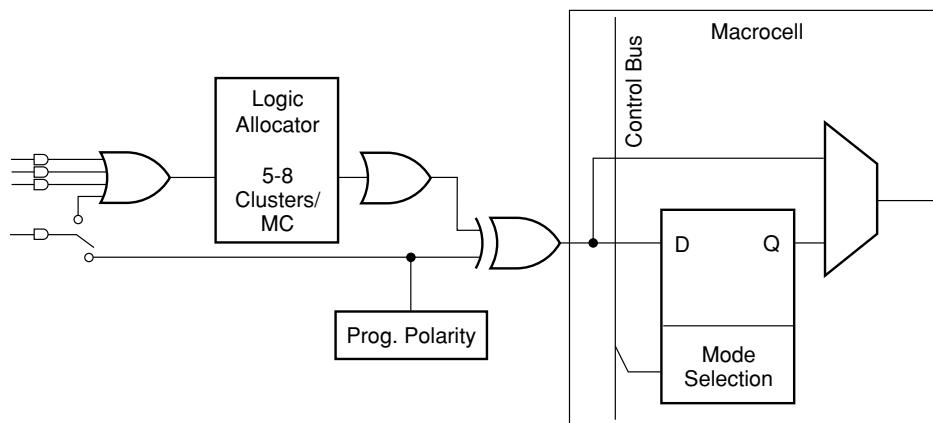
Macrocell	Available Clusters	Macrocell	Available Clusters
M ₀	C ₀ , C ₁ , C ₂ , C ₃ , C ₄	M ₈	C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂
M ₁	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅	M ₉	C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃
M ₂	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆	M ₁₀	C ₇ , C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄
M ₃	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₁	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₄	C ₀ , C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇	M ₁₂	C ₈ , C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₅	C ₁ , C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈	M ₁₃	C ₉ , C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₆	C ₂ , C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉	M ₁₄	C ₁₀ , C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅
M ₇	C ₃ , C ₄ , C ₅ , C ₆ , C ₇ , C ₈ , C ₉ , C ₁₀	M ₁₅	C ₁₁ , C ₁₂ , C ₁₃ , C ₁₄ , C ₁₅

Macrocells

The macrocells for MACH 5 devices consist of a storage element which can be configured for combinatorial, registered or latched operation (Figure 3). The D-type flip-flops can be configured as T-type, J-K, or S-R operation through the use of the XOR gate associated with each macrocell.

Each PAL block has the capability to provide two input registers by using macrocells 0 and 15. In order to use this option, these macrocells must be accessed via the I/O pins associated with macrocells 3 and 12, respectively. Once the macrocell is used as an input register, it cannot be used for logic, so its clusters can be re-directed through the logic allocator to another macrocell. The

I/O pins associated with macrocells 0 and 15 can still be used as input pins. Although the I/O pins for macrocells 3 and 12 are used to connect to the input registers, these macrocells can still be used as “buried” macrocells to drive device logic via the matrix.



20446G-003

Figure 3. Macrocell Diagram

Control Generator

The control generator provides four configurable clock lines and three configurable set/reset lines to each macrocell in a PAL block. Any of the four clock lines and any of the three set/reset lines can be independently selected by any flip-flop within a block. The clock lines can be configured to provide synchronous global (pin) clocks and asynchronous product term clocks, sum term clocks, and latch enables (Figure 4). Three of the four global clocks, as well as two product-term clocks and one sum-term clock, are available per PAL block. Positive or negative edge clocking is available as well as advanced clocking features such as **complementary** and **biphase** clocking. Complementary clocking provides two clock lines exactly 180 degrees out of phase, and is useful in applications such as fast data paths. A biphase clock line clocks flip-flops on both the positive and negative edges of the clock. The configuration options for the four clock lines per PAL block are as follows:

Clock Line 0 Options

- ◆ Global clock (0, 1, 2, or 3) with positive or negative edge clock enable
- ◆ Product-term clock (A^*B^*C)
- ◆ Sum-term clock ($A+B+C$)

Clock Line 1 Options

- ◆ Global clock (0, 1, 2, or 3) with positive edge clock enable
- ◆ Global clock (0, 1, 2, or 3) with negative edge clock enable

MACH 5 TIMING MODEL

The primary focus of the MACH 5 timing model is to accurately represent the timing in a MACH 5 device, and at the same time, be easy to understand. This model accurately describes all combinatorial and registered paths through the device, making a distinction between **internal feedback** and **external feedback**. A signal uses internal feedback when it is fed back into the switch matrix or block without having to go through the output buffer. The input register specifications are also reported as internal feedback. When a signal is fed back into the switch matrix after having gone through the output buffer, it is using external feedback.

The parameter, t_{BUF} is defined as the time it takes to go through the output buffer to the I/O pad. If a signal goes to the internal feedback rather than to the I/O pad, the parameter designator is followed by an “i”. By adding t_{BUF} to this internal parameter, the external parameter is derived. For example, $t_{PD} = t_{PDI} + t_{BUF}$. A diagram representing the modularized MACH 5 timing model is shown in Figure 7. Refer to the Technical Note entitled *MACH 5 Timing and High Speed Design* for a more detailed discussion about the timing parameters.

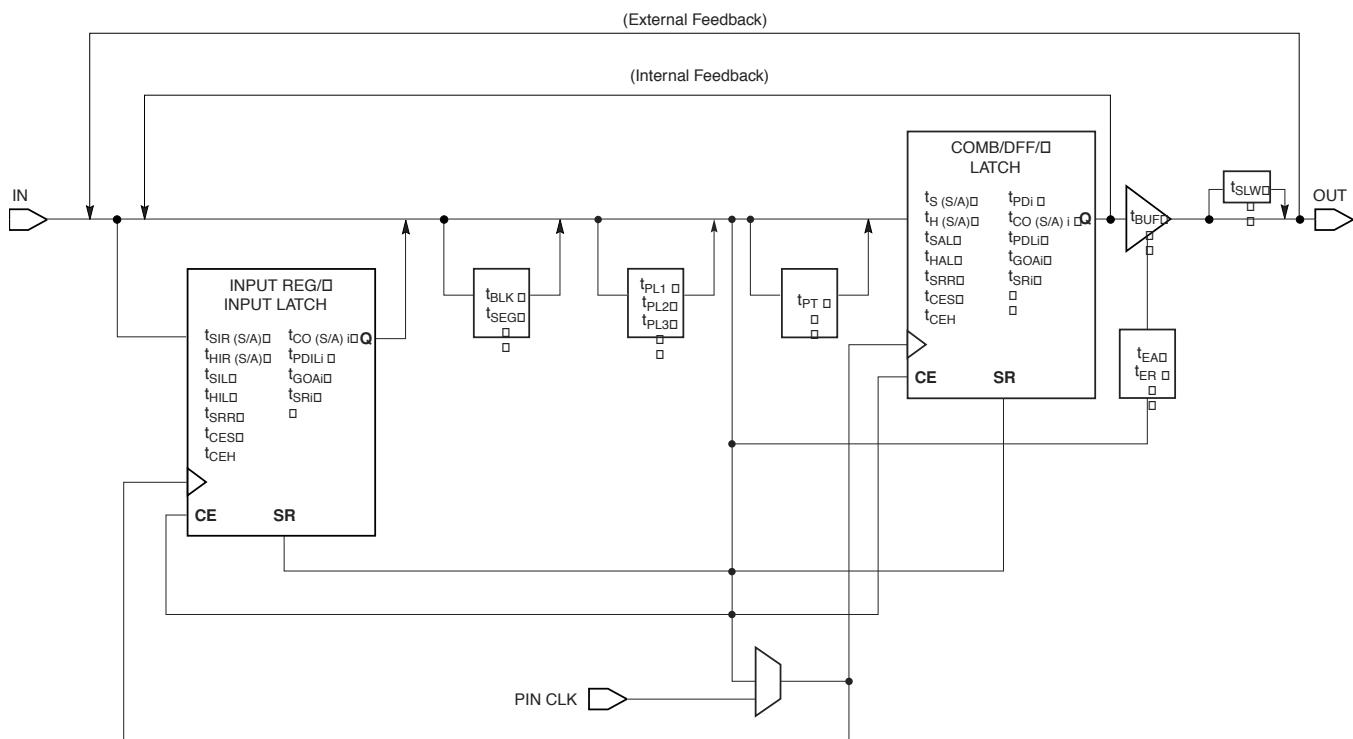
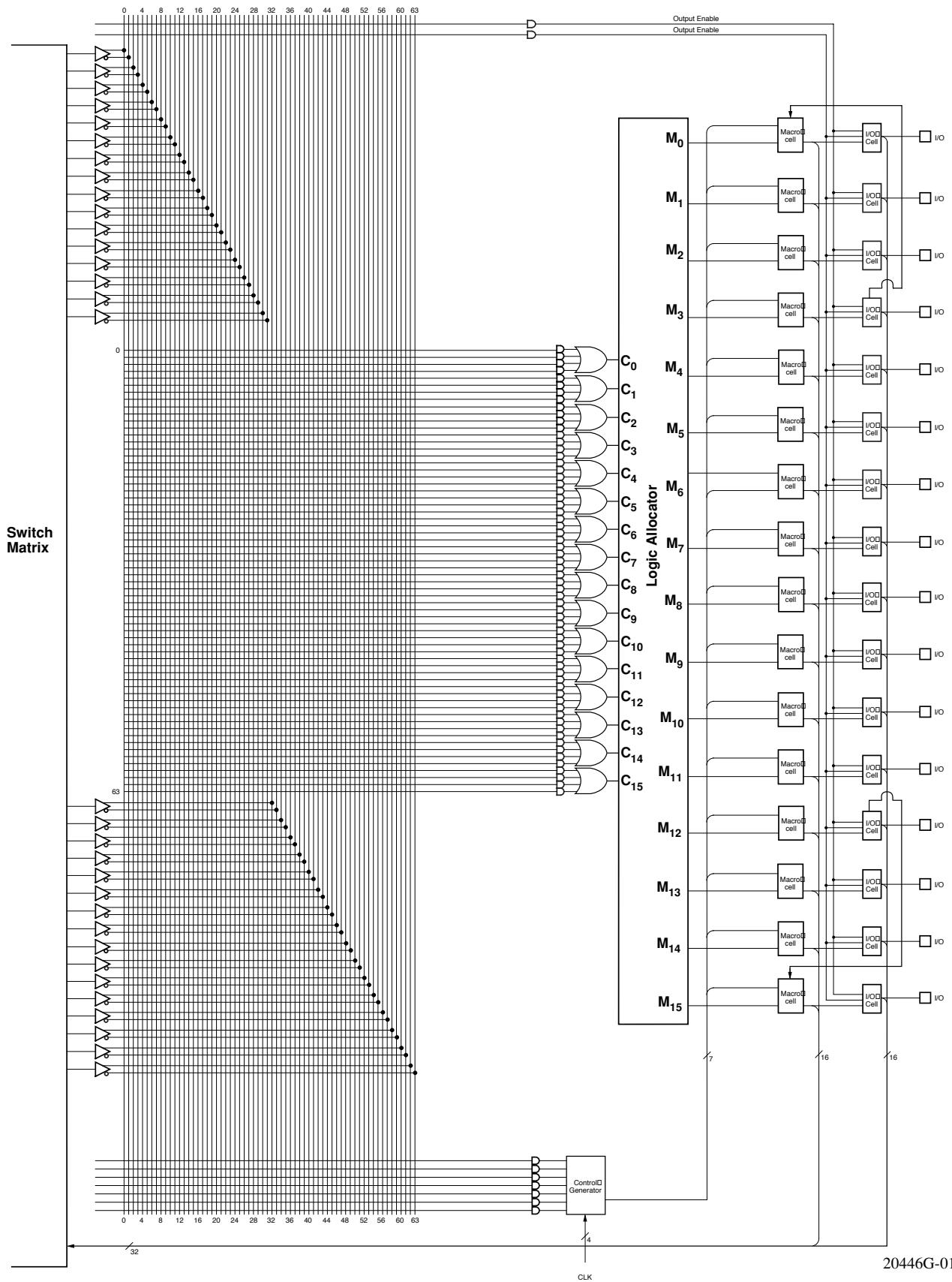


Figure 7. MACH 5 Timing Model

20446G-014

**Select devices have been discontinued.
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MACH 5 PAL BLOCK

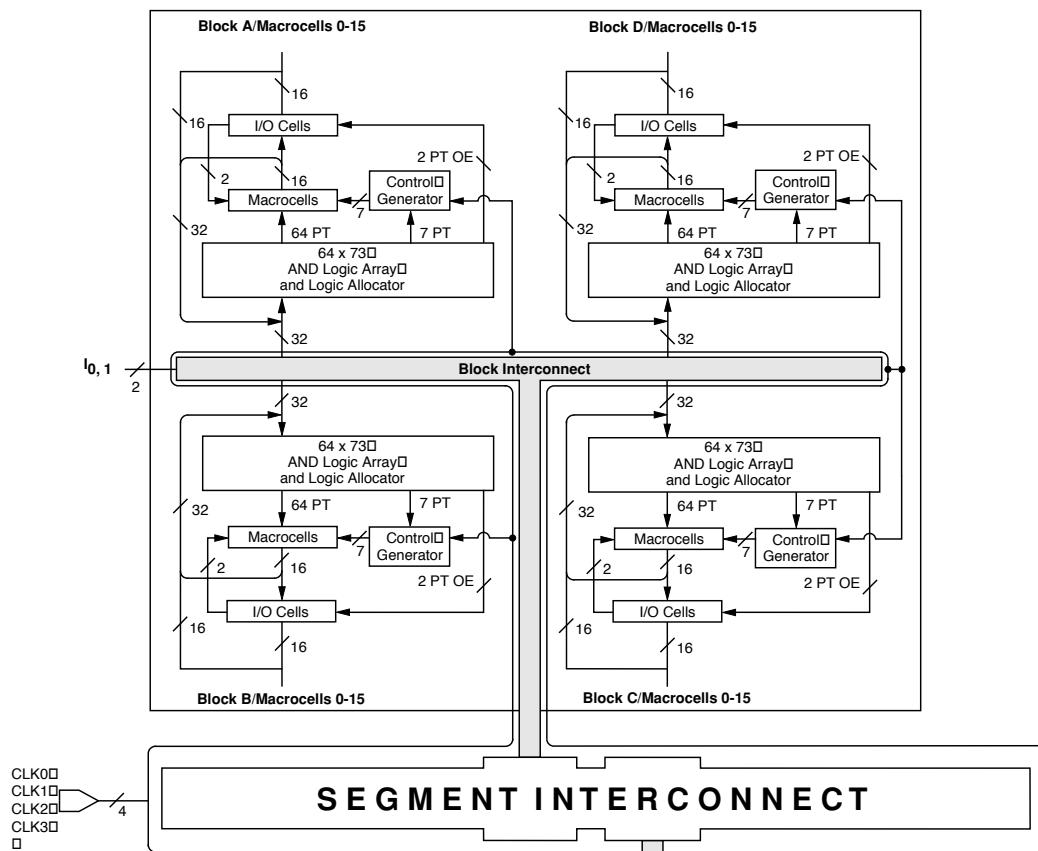


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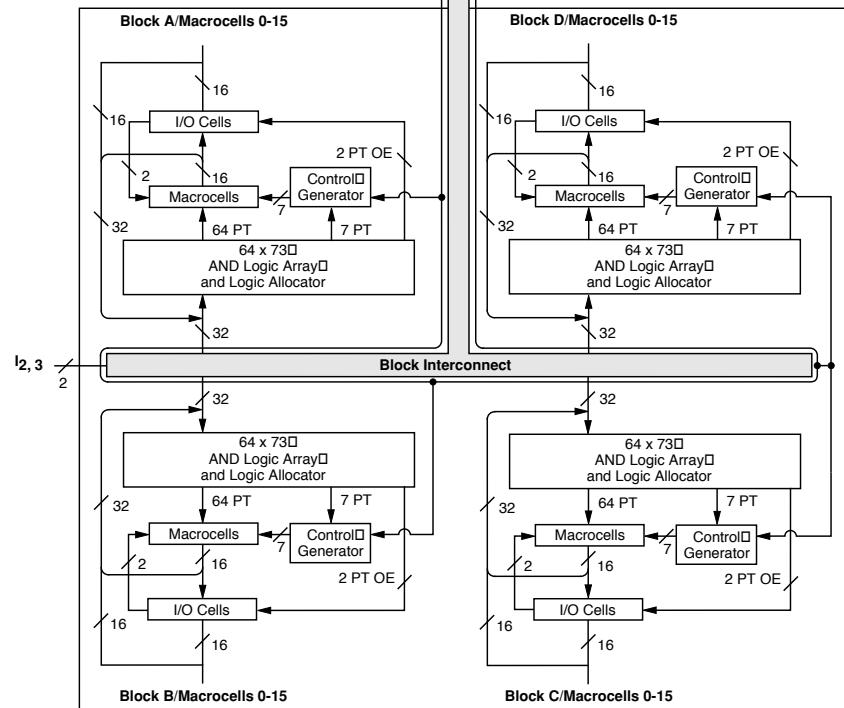
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BLOCK DIAGRAM — M5(LV)-128/XXX

SEGMENT 0



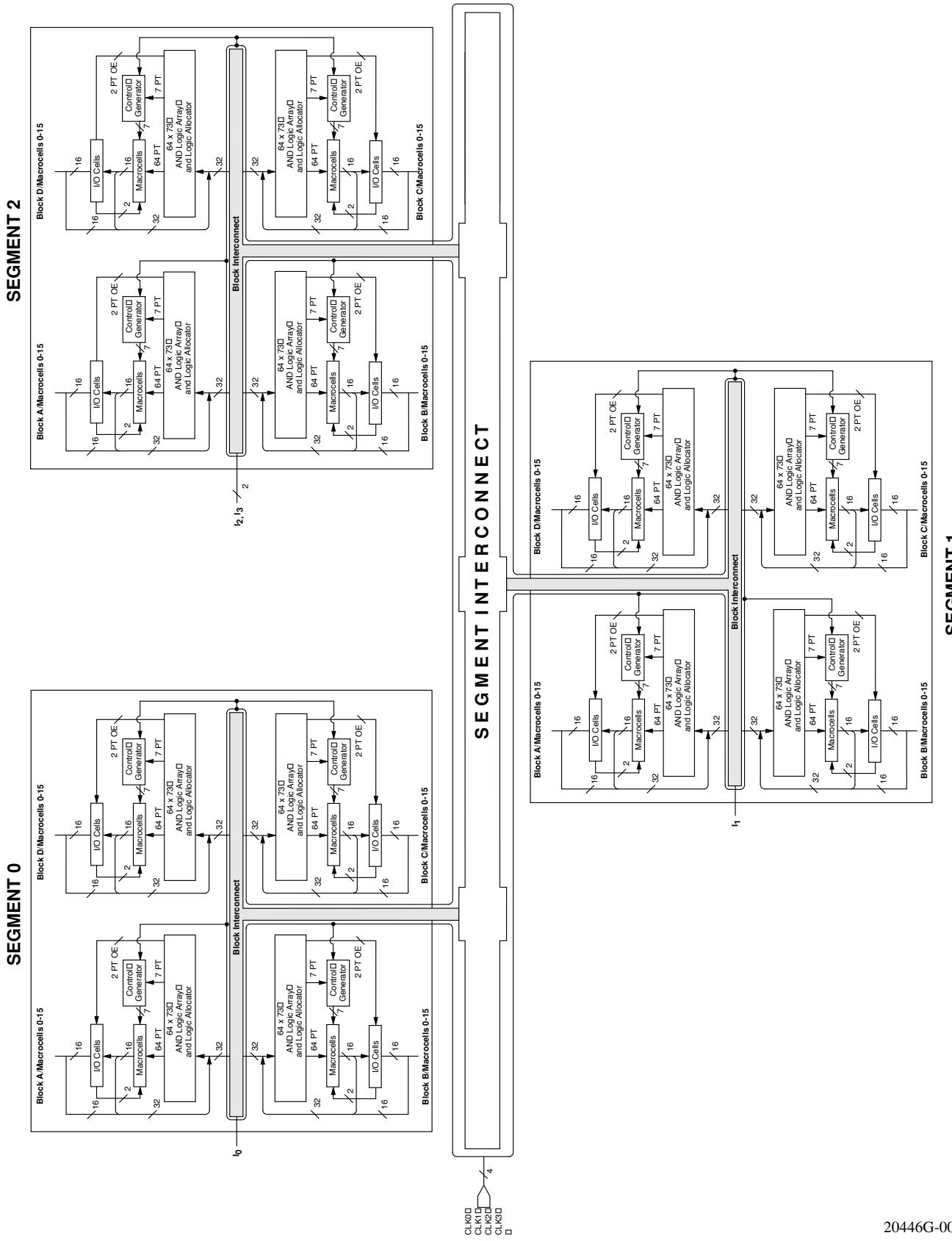
SEGMENT INTERCONNECT



SEGMENT 1

20446G-007

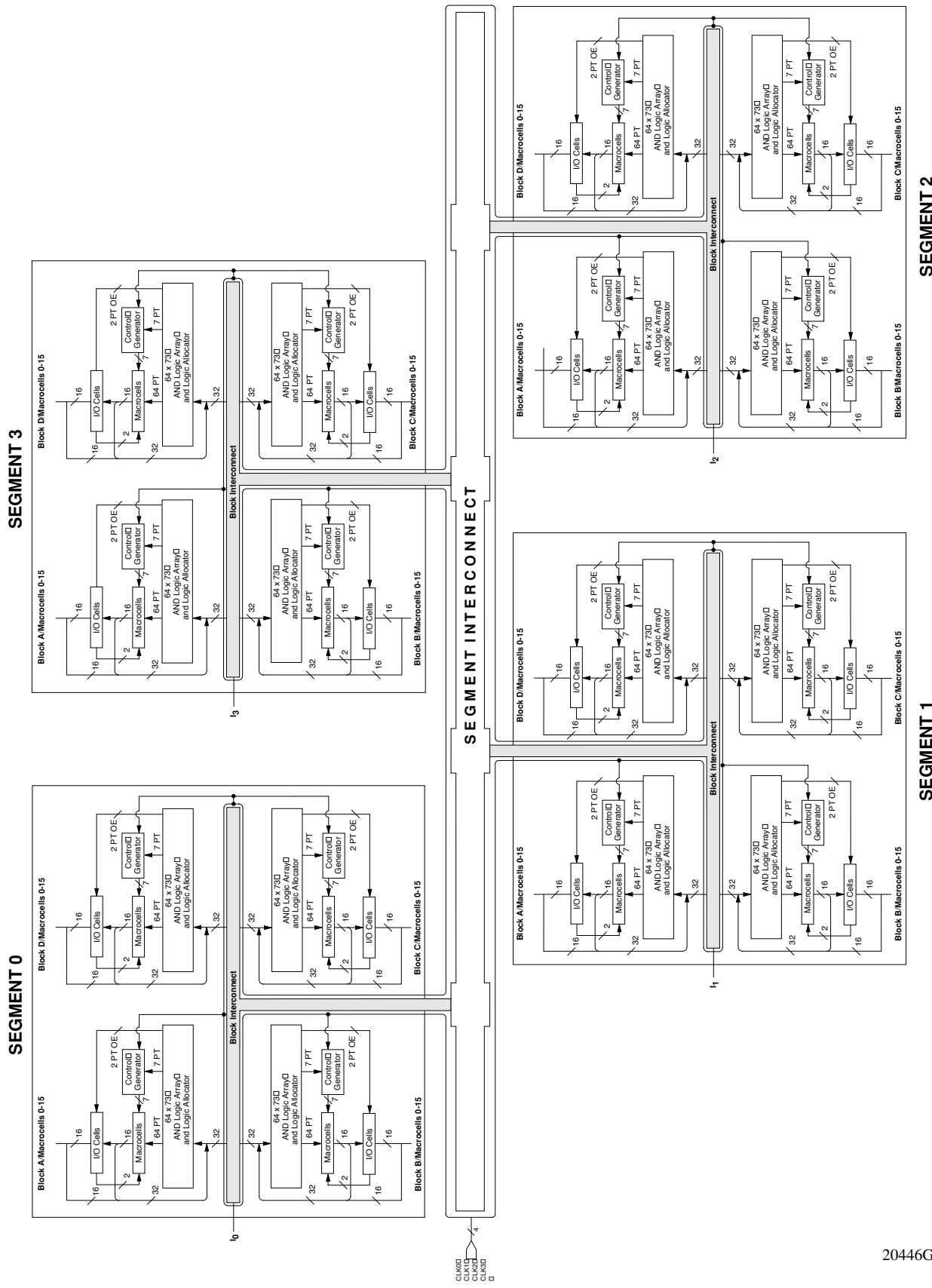
BLOCK DIAGRAM — M5-192/XXX



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BLOCK DIAGRAM — M5(LV)-256/XXX

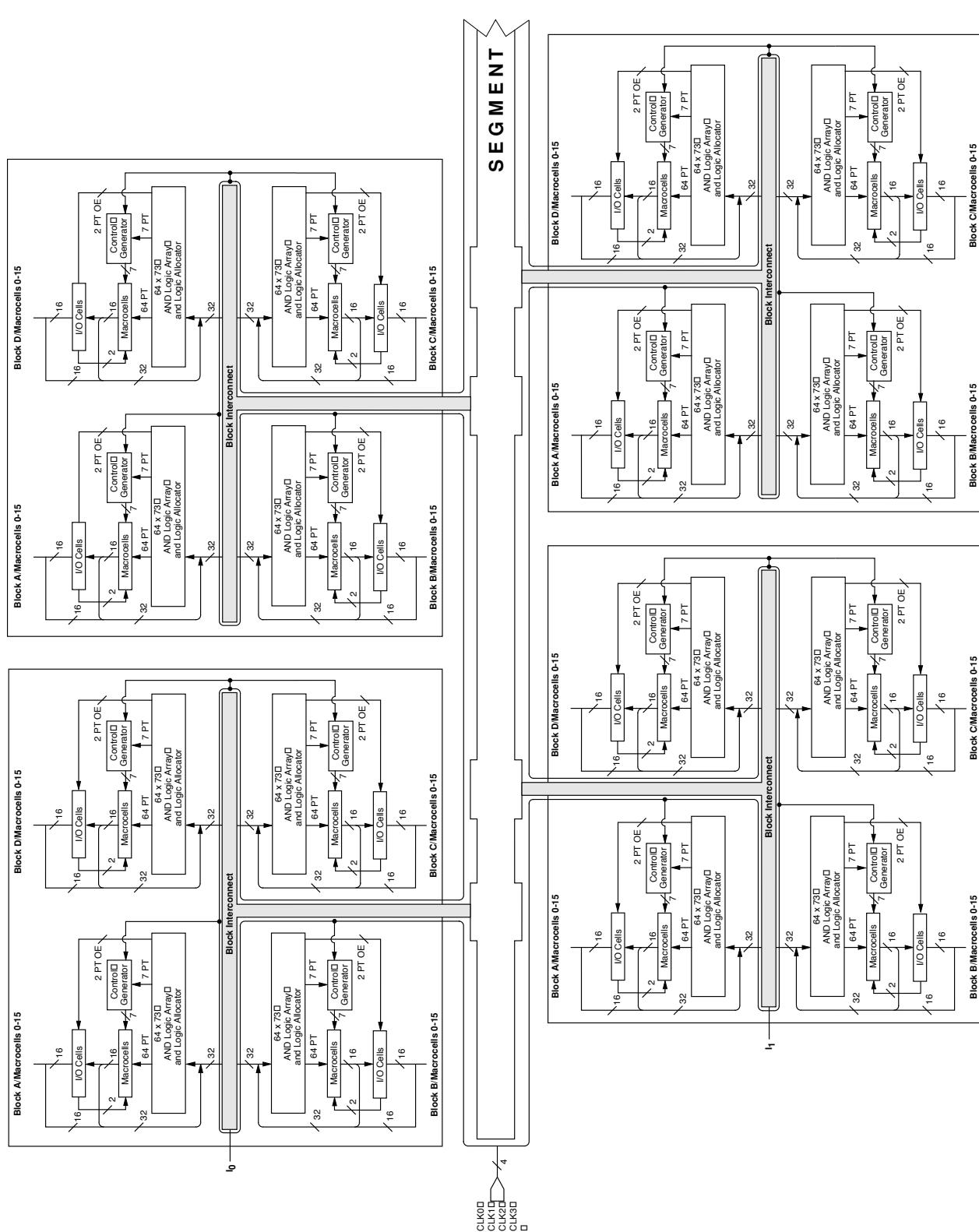


20446G-009

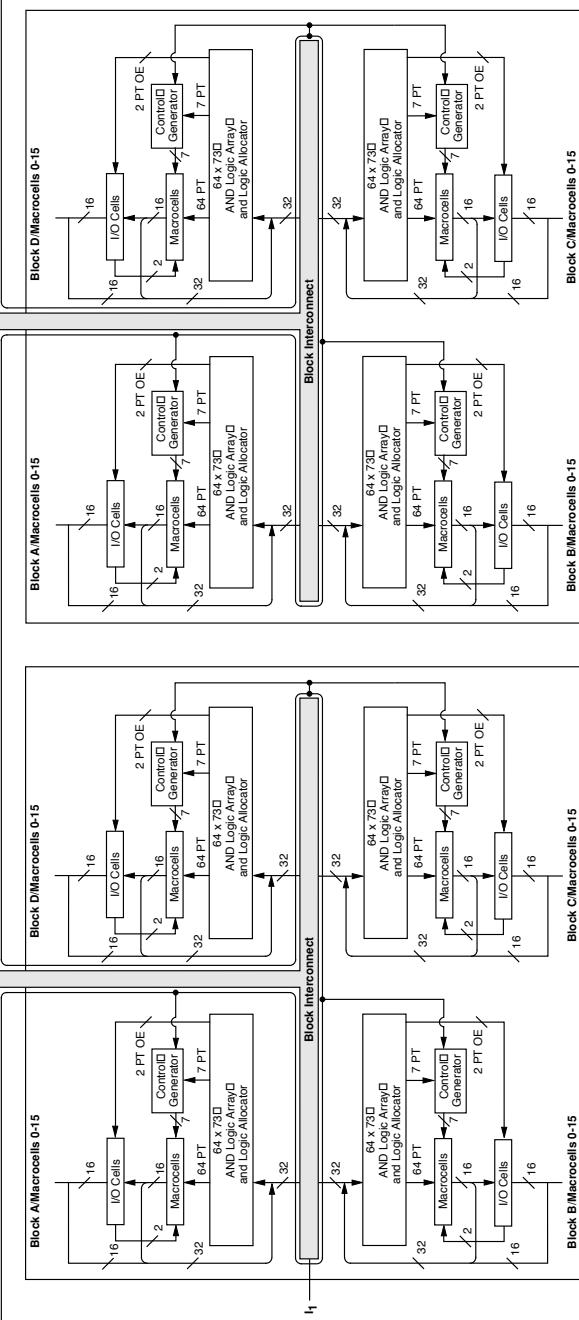
BLOCK DIAGRAM — M5(LV)-512/XXX

Continued

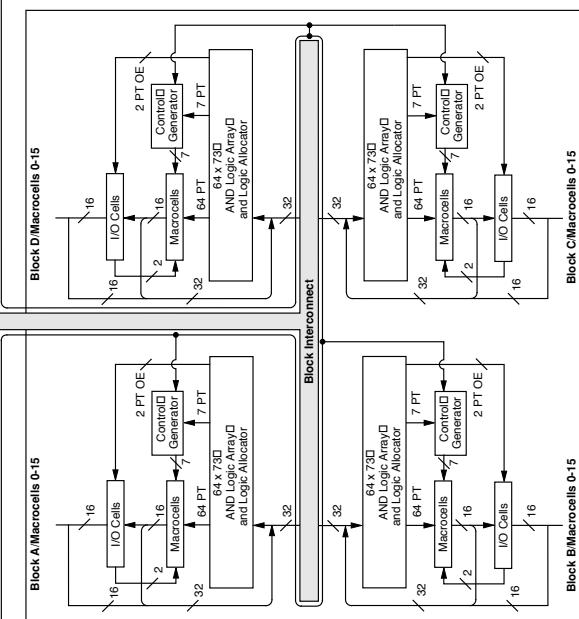
SEGMENT 0



SEGMENT 1



SEGMENT 2



**Select devices have been discontinued.
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Select devices have been discontinued.
See Ordering Information section for product status.

ABSOLUTE MAXIMUM RATINGS

M5

Storage Temperature.....	-65°C to +150°C
Device Junction Temperature (Note 1).....	+130°C or +150°C
Supply Voltage with Respect to Ground	-0.5 V to +7.0 V
DC Input Voltage	-0.5 V to 5.5 V
Static Discharge Voltage.....	2000 V
Latchup Current (-40°C to +85°C)	200 mA
<i>Stresses above those listed under Absolute Maximum Ratings may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to Absolute Maximum Ratings for extended periods may affect device reliability.</i>	

OPERATING RANGES

Commercial (C) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	0°C to +70°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.75 V to +5.25 V

Industrial (I) Devices

Ambient Temperature (T_A)	
Operating in Free Air.....	-40°C to +85°C
Supply Voltage (V_{CC}) with Respect to Ground.....	+4.5 V to +5.5 V
<i>Operating ranges define those limits between which the functionality of the device is guaranteed.</i>	

5-V DC CHARACTERISTICS OVER OPERATING RANGES

Parameter Symbol	Parameter Description	Test Description	Min	Typ	Max	Unit
V_{OH}	Output HIGH Voltage (For M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384, M5-512 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -100 \mu\text{A}, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$		3.3	3.6	V
	Output HIGH Voltage (For M5-128, M5-192, M5-256 Devices)	$I_{OH} = -3.2 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$	2.4			V
		$I_{OH} = -2.5 \text{ mA}, V_{CC} = 5.25 \text{ V}, V_{IN} = V_{IH} \text{ or } V_{IL}$			3.6	V
V_{OL}	Output LOW Voltage (Note 2)	$I_{OL} = +16 \text{ mA}, V_{CC} = \text{Min}, V_{IN} = V_{IH} \text{ or } V_{IL}$			0.5	V
V_{IH}	Input HIGH Voltage	Guaranteed Input Logical HIGH Voltage for all Inputs (Note 3)	2.0			V
V_{IL}	Input LOW Voltage	Guaranteed Input Logical LOW Voltage for all Inputs (Note 3)			0.8	V
I_{IH}	Input HIGH Leakage Current	$V_{IN} = 5.25, V_{CC} = \text{Max}$ (Note 4)			10	μA
I_{IL}	Input LOW Leakage Current	$V_{IN} = 0, V_{CC} = \text{Max}$ (Note 4)			-10	μA
I_{OZH}	Off-State Output Leakage Current HIGH	$V_{OUT} = 5.25, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			10	μA
I_{OZL}	Off-State Output Leakage Current LOW	$V_{OUT} = 0, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 4)			-10	μA
I_{SC}	Output Short-Circuit Current	$V_{OUT} = 0.5 \text{ V}, V_{CC} = \text{Max}, V_{IN} = V_{IH} \text{ or } V_{IL}$ (Note 5)	-30		-180	mA

Note:

- 150° for M5-128, M5-192 and M5-256 devices. 130° for M5-128/1, M5-192/1, M5-256/1, M5-320, M5-384 and M5-512 devices.
- Total I_{OL} between ground pins should not exceed 64 mA.
- These are absolute values with respect to device ground, and all overshoots due to system and/or tester noise are included.
- I/O pin leakage is the worst case of I_{IL} and I_{OZL} or I_{IH} and I_{OZH} .
- Not more than one output should be shorted at a time. Duration of the short-circuit should not exceed one second.

Select devices have been discontinued.
See Ordering Information section for product status.

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹

	-5		-6		-7		-10		-12		-15		-20		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Combinatorial Delay:																
t _{PDI}	Internal combinatorial propagation delay		3.5		4.5		5.5		8.0		10.0		13.0		18.0	ns
t _{PD}	Combinatorial propagation delay		5.5		6.5		7.5		10.0		12.0		15.0		20.0	ns
Registered Delays:																
t _{SS}	Synchronous clock setup time	3.0		3.0		4.0		5.0		6.0		8.0		10.0		ns
t _{SA}	Asynchronous clock setup time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HS}	Synchronous clock hold time	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HA}	Asynchronous clock hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{COSI}	Synchronous clock to internal output		2.5		3.0		4.0		5.0		6.0		8.0		10.0	ns
t _{COS}	Synchronous clock to output		4.5		5.0		6.0		7.0		8.0		10.0		12.0	ns
t _{COAi}	Asynchronous clock to internal output		6.0		6.0		8.0		10.0		13.0		15.0		18.0	ns
t _{COA}	Asynchronous clock to output		8.0		8.0		10.0		12.0		15.0		17.0		20.0	ns
Latched Delays:																
t _{SAL}	Latch setup time	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{HAL}	Latch hold time	3.0		3.0		4.0		5.0		6.0		7.0		8.0		ns
t _{PDLi}	Transparent latch internal		6.0		7.0		7.0		8.0		9.0		10.0		10.0	ns
t _{PDL}	Propagation delay through transparent latch		8.0		9.0		9.0		10.0		11.0		12.0		12.0	ns
t _{GOAi}	Gate to internal output		7.0		8.0		8.0		9.0		10.0		11.0		12.0	ns
t _{GOA}	Gate to output		9.0		10.0		10.0		11.0		12.0		13.0		14.0	ns
Input Register Delays:																
t _{SIRS}	Input register setup time using a synchronous clock	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{SIRA}	Input register setup time using an asynchronous clock	0.0		0.0		0.0		0.0		0.0		0.0		0.0		ns
t _{HIRS}	Input register hold time using a synchronous clock	3.0		3.0		3.0		4.0		4.0		4.0		4.0		ns
t _{HIRA}	Input register hold time using an asynchronous clock	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
Input Latch Delays:																
t _{SIL}	Input latch setup time	2.0		2.0		2.0		3.0		3.0		3.0		3.0		ns
t _{HIL}	Input latch hold time	6.0		6.0		6.0		7.0		7.0		7.0		7.0		ns
t _{PDILI}	Transparent input latch		5.0		5.0		5.5		6.0		6.0		6.0		6.0	ns
Output Delays:																
t _{BUF}	Output buffer delay		2.0		2.0		2.0		2.0		2.0		2.0		2.0	ns
t _{SLW}	Slow slew rate delay		2.5		2.5		2.5		2.5		2.5		2.5		2.5	ns
t _{EA}	Output enable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns
t _{ER}	Output disable time		7.5		7.5		9.5		10.0		12.0		15.0		20.0	ns

**Select devices have been discontinued.
See Ordering Information section for product status.**

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

	-5		-6		-7		-10		-12		-15		-20		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Power Delays:																
t _{PL1}	Power level 1 delay (Note 2)		4.0 (5.0)		4.0		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)		4.0 (5.0)	ns
t _{PL2}	Power level 2 delay (Note 2)		6.0 (9.0)		6.0		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)		6.0 (9.0)	ns
t _{PL3}	Power level 3 delay (Note 2)		9.0 (17.5)		9.0		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)		9.0 (17.5)	ns
Additional Cluster Delay:																
t _{PT}	Product term cluster delay		0.3		0.3		0.3		0.3		0.3		0.3		0.3	ns
Interconnect Delays:																
t _{BLK}	Block interconnect delay		1.5		1.5		1.5		2.0		2.0		2.0		2.0	ns
t _{SEG}	Segment interconnect delay		4.5		4.5		5.0		6.0		6.0		6.0		6.0	ns
Reset and Preset Delays:																
t _{SRI}	Asynchronous reset or preset to internal register output		6.0		8.0		8.0		10.0		12.0		14.0		16.0	ns
t _{SR}	Asynchronous reset or preset to register output		8.0		10.0		10.0		12.0		14.0		16.0		18.0	ns
t _{SRR}	Reset and set register recovery time	5.5		7.5		7.5		8.0		9.0		10.0		11.0		ns
t _{SRW}	Asynchronous reset or preset width	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
Clock Enable Delays:																
t _{CES}	Clock enable setup time	4.0		5.0		5.0		6.0		7.0		7.0		8.0		ns
t _{CEH}	Clock enable hold time	3.0		4.0		4.0		5.0		6.0		6.0		7.0		ns
Width:																
t _{WLS}	Global clock width low (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WHS}	Global clock width high (Note 3)	2.5		3.0		3.0		4.0		5.0		6.0		6.0		ns
t _{WLA}	Product term clock width low	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WHA}	Product term clock width high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{GWA}	Gate width low (for low transparent) or high (for high transparent)	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns
t _{WIR}	Input register clock width low or high	3.0		4.0		4.0		5.0		6.0		7.0		8.0		ns

M5(LV) TIMING PARAMETERS OVER OPERATING RANGES¹ (CONTINUED)

	-5		-6		-7		-10		-12		-15		-20		Unit	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max		
Frequency:																
f_{MAX}	External feedback, PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COS})$	133		125		100		83.3		71.4		55.6		45.5		MHz
	Internal feedback, PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{COSi})$	182		167		125		100		83.3		62.5		50.0		MHz
	No feedback PAL block level. Min of $1/(t_{WLS} + t_{WHS})$ or $1/(t_{SS} + t_{HS})$	200		167		167		125		100		83.3		83.3		MHz
f_{MAXA}	External feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COA})$	91		91		71.4		58.8		47.6		41.7		35.7		MHz
	Internal feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{COAi})$	111		111		83.3		66.7		52.6		45.5		38.5		MHz
	No feedback, PAL block level. Min of $1/(t_{WLA} + t_{WHA})$ or $1/(t_{SA} + t_{HA})$	167		125		125		100		83.3		71.4		62.5		MHz
f_{MAXI}	Maximum input register frequency $1/(t_{SIRS} + t_{HIRS})$ or $1/(2 \times t_{WICW})$	167		125		125		100		83.3		71.4		62.5		MHz

Notes:

1. See "MACH Switching Test Circuits" documentation on the Lattice Data Book CD-ROM or Lattice web site.
2. Numbers in parentheses are for M5-128, M5-192, M5-256.
3. If a signal is used as both a clock and a logic array input, then the maximum input frequency applies ($f_{MAX}/2$).

Select devices have been discontinued.
See Ordering Information section for product status.

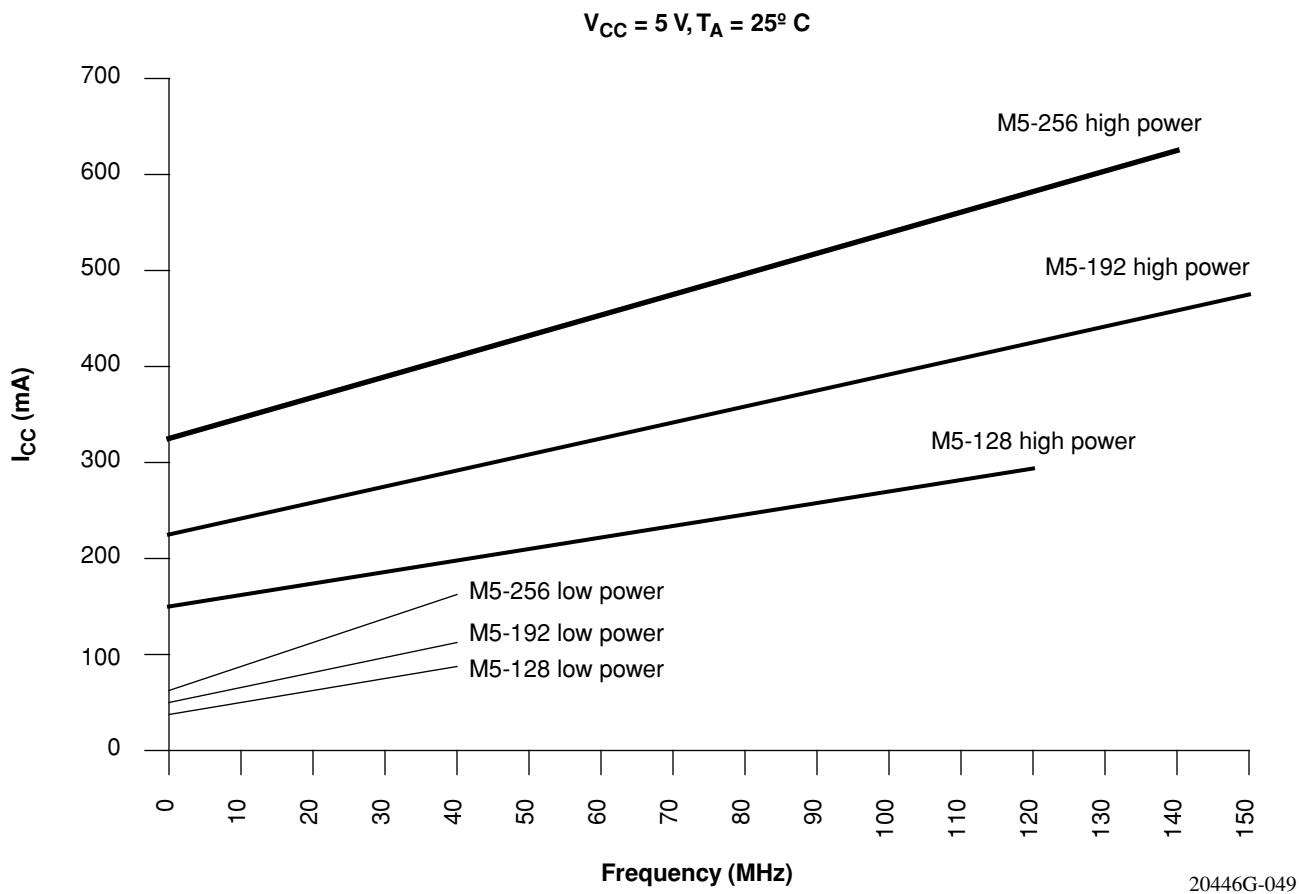


Figure 9. I_{CC} Curves at High/Low Power Modes

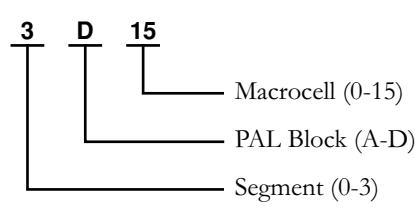
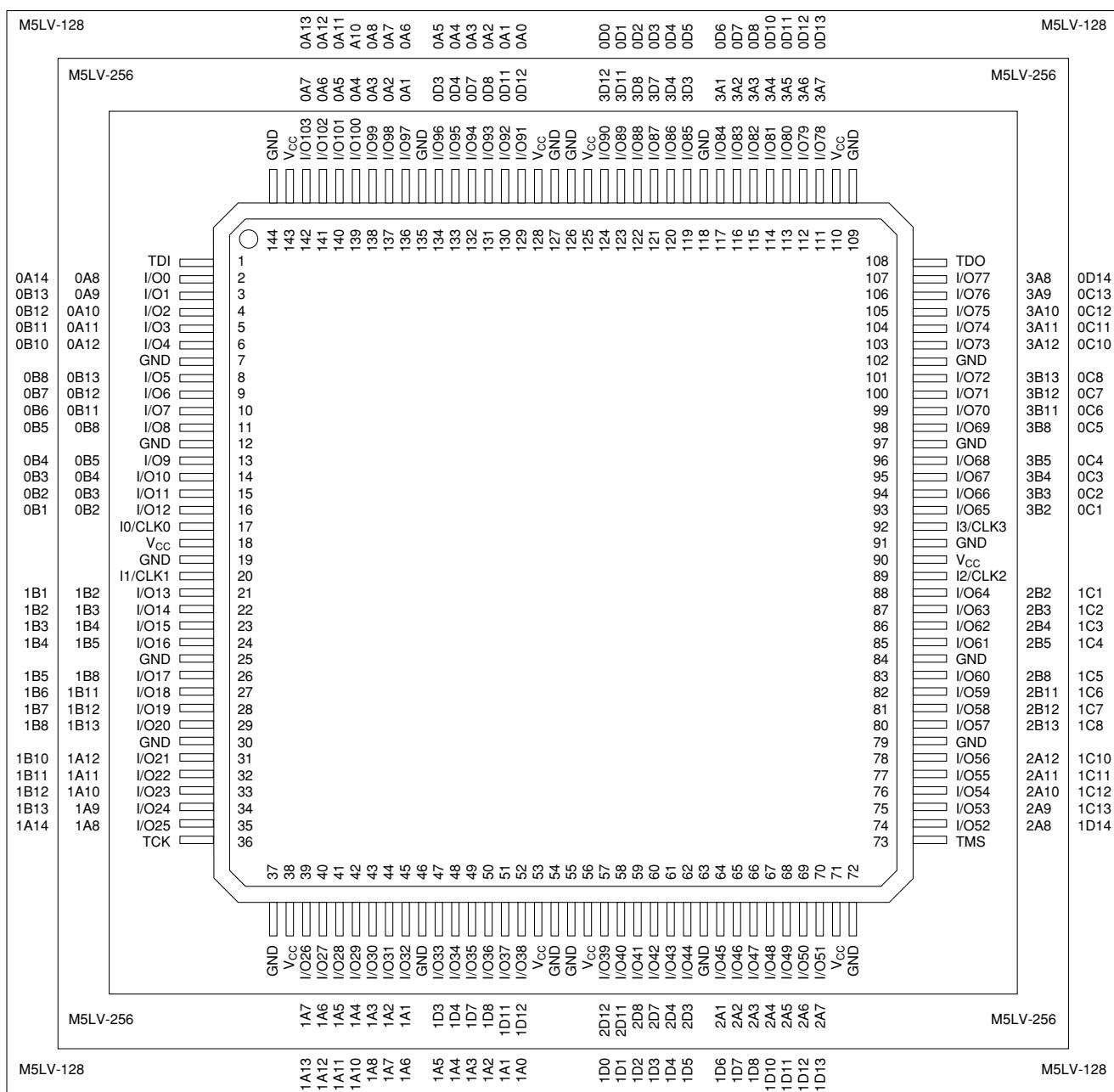
Select devices have been discontinued.
See Ordering Information section for product status.

Select devices have been discontinued.
See Ordering Information section for product status.

144-PIN TQFP CONNECTION DIAGRAM

Top View

144-Pin TQFP



20446G-020

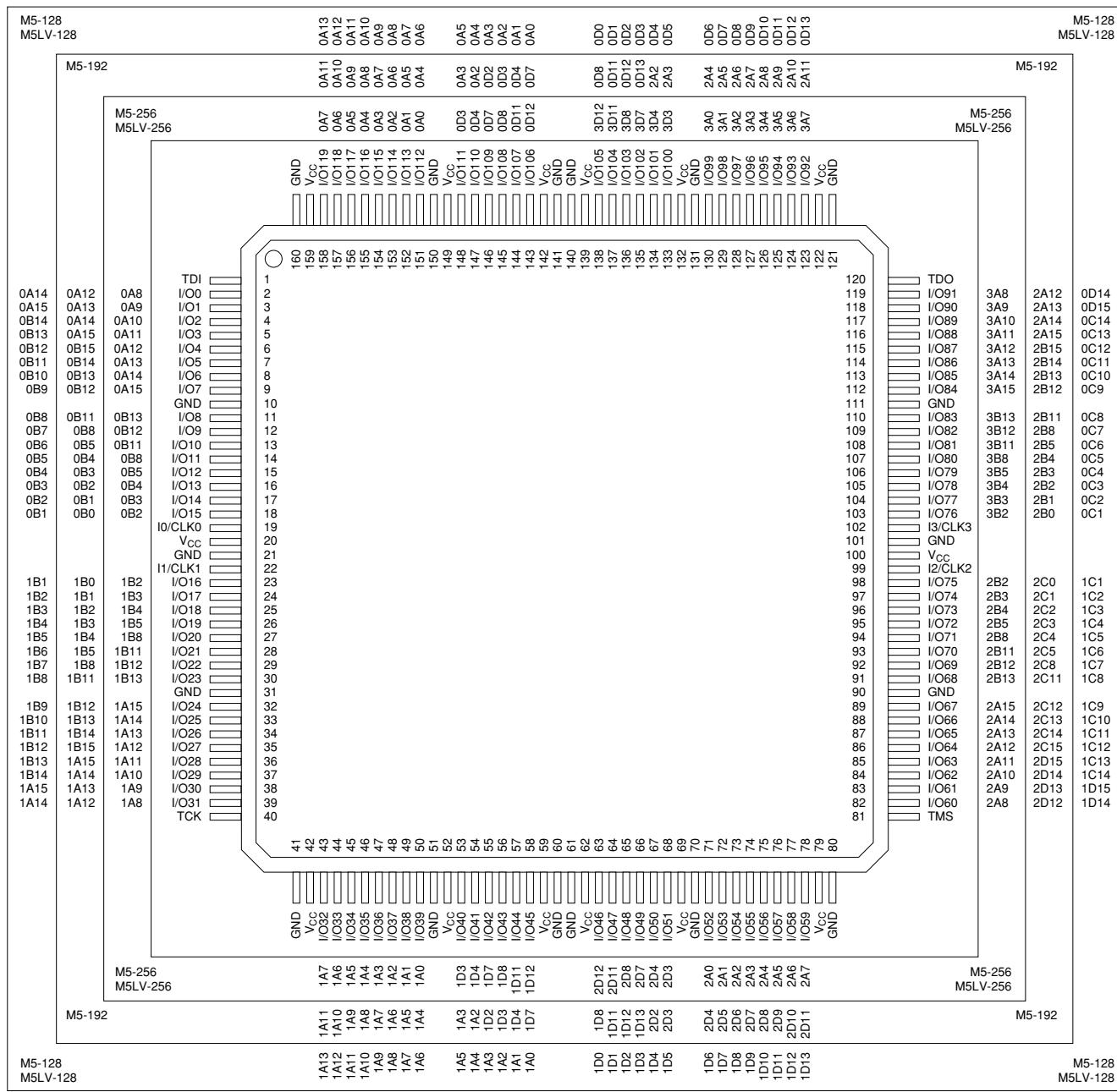
Pin Designations

CLK	=	Clock
GND	=	Ground
I	=	Input
I/O	=	Input/Output
NC	=	No Connect
V _{CC}	=	Supply Voltage
TDI	=	Test Data In
TCK	=	Test Clock
TMS	=	Test Mode Select
TDO	=	Test Data Out

160-PIN PQFP CONNECTION DIAGRAM

Top View

160-Pin PQFP (128, 192, 256 Macrocells)



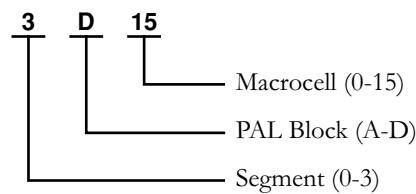
20446G-021

Select devices have been discontinued.
See Ordering Information section for product status.

Pin Designations

CLK	= Clock
GND	= Ground
I	= Input
I/O	= Input/Output
NC	= No Connect

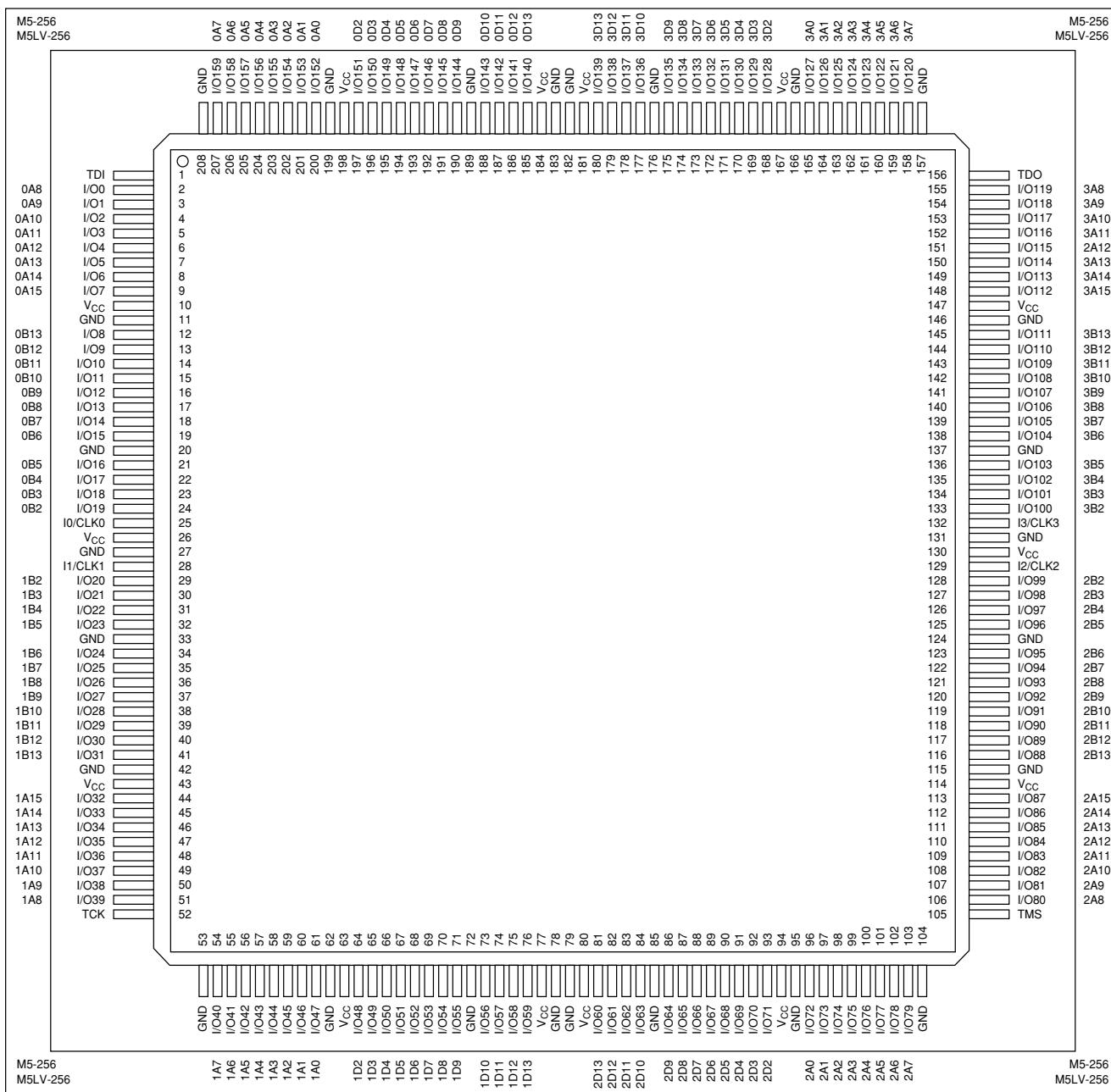
V _{CC}	= Supply Voltage
TDI	= Test Data In
TCK	= Test Clock
TMS	= Test Mode Select
TDO	= Test Data Out



208-PIN PQFP CONNECTION DIAGRAM

Top View

208-Pin PQFP (256 Macrocells)

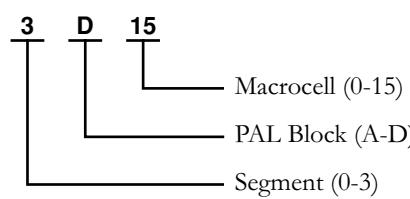


20446G-023

Select devices have been discontinued.
See Ordering Information section for product status.

Pin Designations

CLK	= Clock	V _{CC}	= Supply Voltage
GND	= Ground	TDI	= Test Data In
I	= Input	TCK	= Test Clock
I/O	= Input/Output	TMS	= Test Mode Select
NC	= No Connect	TDO	= Test Data Out

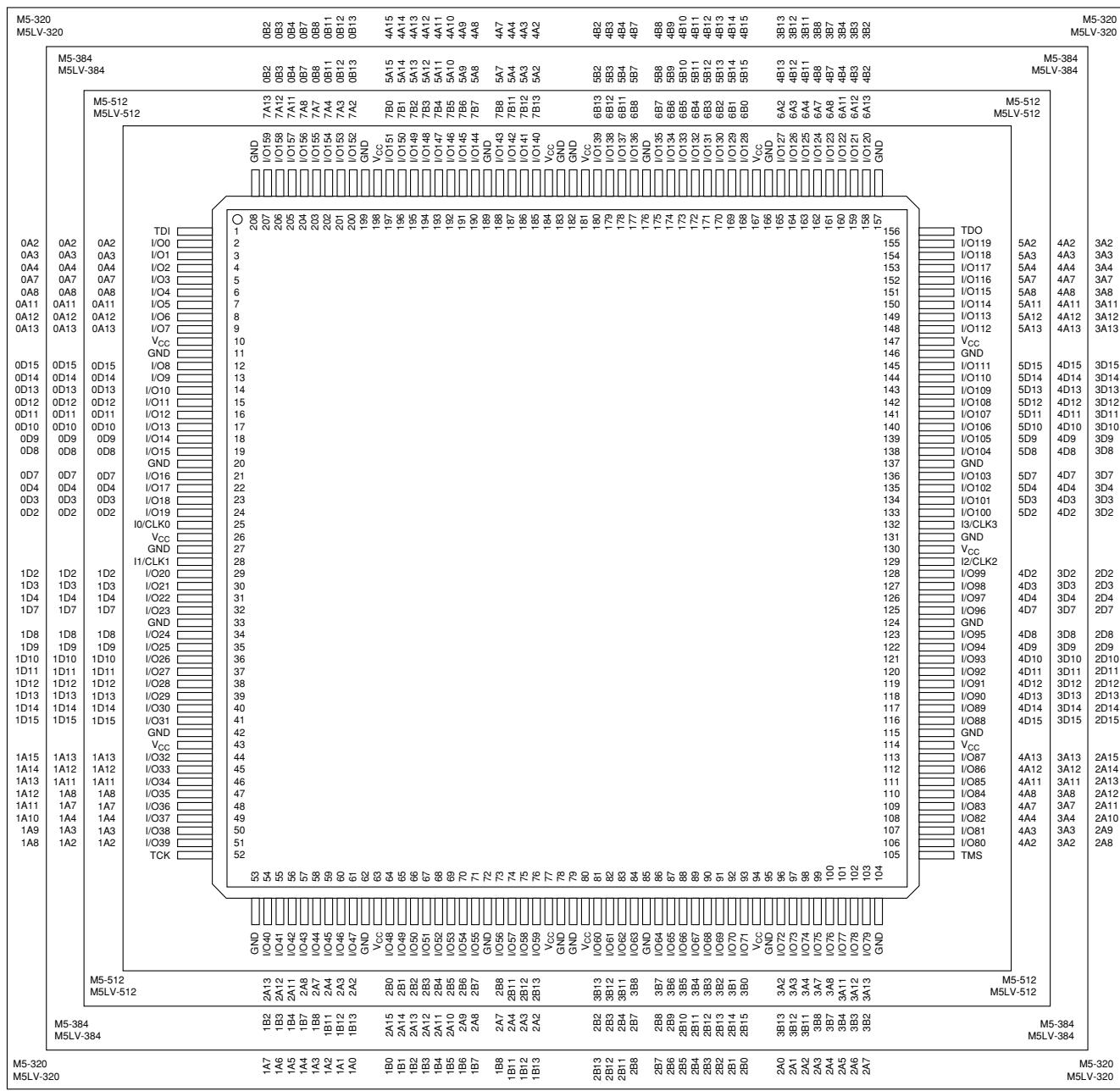


See Ordering Information section for product status.

208-PIN PQFP (WITH INTERNAL HEAT SPREADER) CONNECTION DIAGRAM

Top View

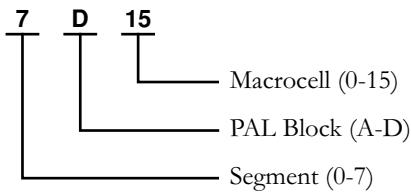
208-Pin PQFP (320, 384, 512 Macrocells)



20446G-024

Pin Designations

CLK	= Clock	V _{CC}	= Supply Voltage
GND	= Ground	TDI	= Test Data In
I	= Input	TCK	= Test Clock
I/O	= Input/Output	TMS	= Test Mode Select
NC	= No Connect	TDO	= Test Data Out



256-BALL BGA CONNECTION DIAGRAM — M5-320

Bottom View (I/O Pin-outs)

256-Ball BGA

	20	19	18	17	16	15	14	13	12	11	10	9	8	7	6	5	4	3	2	1		
A	GND	I/O11	GND	I/O44	I/O58	GND	I/O70	I/O76	GND	GND	I/O108	I/O116	GND	I/O128	I/O134	GND	GND	GND	A			
B	GND	I/O12	I/O28	I/O45	I/O59	I/O64	I/O71	I/O77	I/O84	I/O90	I/O96	I/O102	I/O117	I/O122	I/O129	I/O135	I/O148	I/O164	GND	B		
C	I/O0	I/O13	V _{CC}	I/O46	I/O60	I/O65	I/O72	I/O78	I/O85	I/O91	I/O97	I/O103	I/O110	I/O118	I/O123	I/O130	I/O136	V _{CC}	I/O165	I/O181	C	
D	I/O1	I/O14	I/O29	V _{CC}	V _{CC}	I/O66	V _{CC}	I/O79	I/O86	I/O92	I/O98	I/O104	I/O111	V _{CC}	I/O124	V _{CC}	V _{CC}	I/O149	I/O166	I/O182	D	
E	I/O2	I/O15	I/O30	TDI											TDO	I/O150	I/O167	I/O183	E			
F	GND	I/O16	I/O31	I/O47											I/O137	I/O151	I/O168	GND	F			
G	I/O3	I/O17	I/O32	V _{CC}											V _{CC}	I/O152	I/O169	I/O184	G			
H	GND	I/O18	I/O33	I/O48											I/O138	I/O153	I/O170	GND	H			
J	I/O4	I/O19	I/O34	I/O49											I/O139	I/O154	I/O171	I/O185	J			
K	GND	I/O1CK0	I/O35	I/O50											I/O140	I/O155	I ₃ /CLK3	I/O186	K			
L	I/O5	I ₁ /CLK1	I/O36	I/O51											I/O141	I/O156	I ₂ /CLK2	GND	L			
M	I/O6	I/O20	I/O37	I/O52											I/O142	I/O157	I/O172	I/O187	M			
N	GND	I/O21	I/O38	I/O53											I/O143	I/O158	I/O173	GND	N			
P	I/O7	I/O22	I/O39	V _{CC}											V _{CC}	I/O159	I/O174	I/O188	P			
R	GND	I/O23	I/O40	I/O54												I/O144	I/O160	I/O175	GND	R		
T	I/O8	I/O24	I/O41	TCK											TMS	I/O161	I/O176	I/O189	T			
U	I/O9	I/O25	I/O42	V _{CC}	V _{CC}	I/O67	V _{CC}	I/O80	I/O87	I/O93	I/O99	I/O105	I/O112	V _{CC}	I/O125	V _{CC}	V _{CC}	I/O162	I/O177	I/O190	U	
V	I/O10	I/O26	V _{CC}	I/O55	I/O61	I/O68	I/O73	I/O81	I/O88	I/O94	I/O100	I/O106	I/O113	I/O119	I/O126	I/O131	I/O145	V _{CC}	I/O178	I/O191	V	
W	GND	I/O27	I/O43	I/O56	I/O62	I/O69	I/O74	I/O82	I/O89	I/O95	I/O101	I/O107	I/O114	I/O120	I/O127	I/O132	I/O146	I/O163	I/O179	GND	W	
Y	GND	GND	GND	I/O57	I/O63	GND	I/O75	I/O83	GND	GND	GND	GND	GND	I/O115	I/O121	GND	I/O133	I/O147	GND	I/O180	GND	Y

Pin Designations

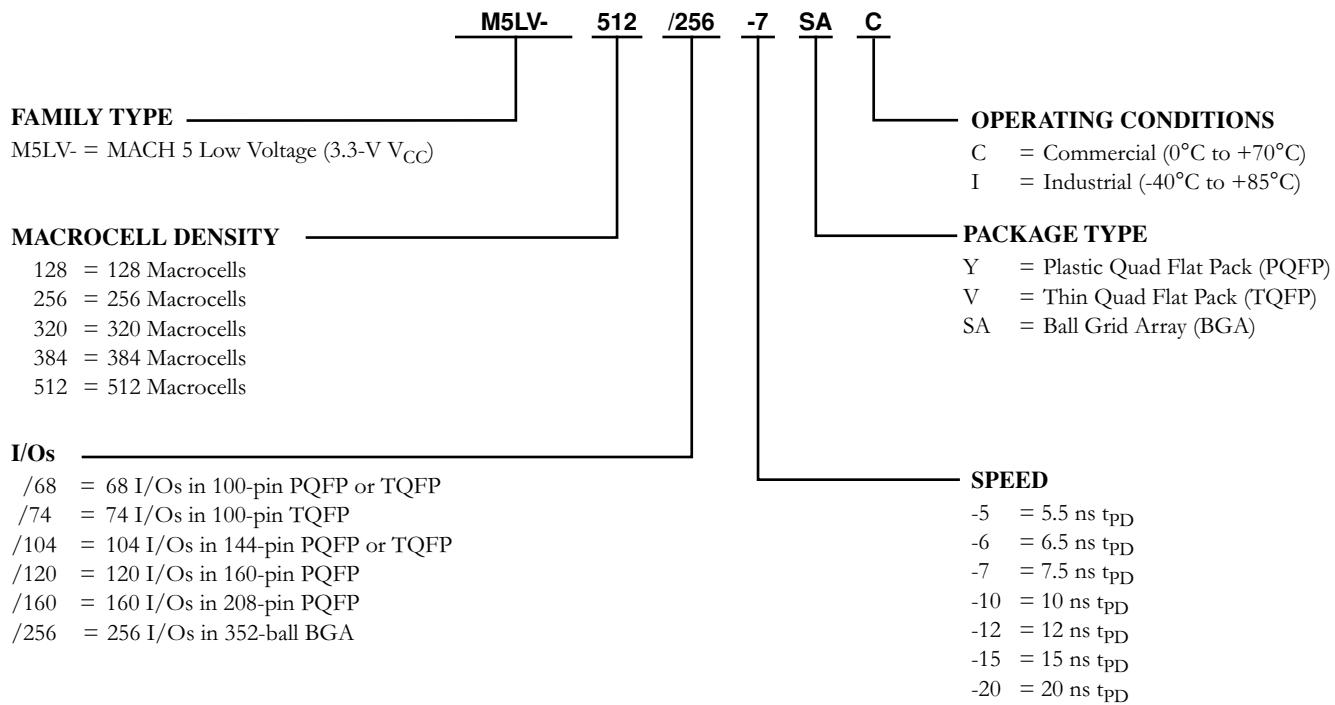
- CLK = Clock
- GND = Ground
- I = Input
- I/O = Input/Output
- NC = No Connect
- V_{CC} = Supply Voltage
- TDI = Test Data In
- TCK = Test Clock
- TMS = Test Mode Select
- TDO = Test Data Out

Select devices have been discontinued.
See Ordering Information section for product status.

Select devices have been discontinued.
See Ordering Information section for product status.

3.3V M5LV ORDERING INFORMATION¹

Lattice standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of the elements below.



Note:

1. See below for valid device/package combinations.

Valid Combinations		
M5LV-128/68		VC, VI
M5LV-128/74		VC, VI
M5LV-128/104		VC, VI
M5LV-128/120	Commercial: -5, -7, -10, -12	YC, YI
M5LV-256/68		YC, YI
M5LV-256/74	Industrial: -7, -10, -12, -15	VC, VI
M5LV-256/104		VC, VI
M5LV-256/120		YC, YI
M5LV-256/160		YC, YI

Device Marking

Actual device marking differs from the ordering part number (OPN). All MACH devices are dual-marked with both Commercial and Industrial grades. The Industrial grade is slower, i.e., M5LV-512/256-7AC-10AI.

Valid Combinations		
M5LV-320/120		YC, YI
M5LV-320/160	Commercial: -6, -7, -10, -12, -15	YC, YI
M5LV-384/120		YC, YI
M5LV-384/160		YC, YI
M5LV-512/120	Industrial: -10, -12, -15, -20	YC, YI
M5LV-512/160		YC, YI
M5LV-512/256		SAC, SAI

Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult the local Lattice sales office to confirm availability of specific valid combinations and to check on newly released combinations.